

A3  
and removing at least part of the encapsulant to produce a modified PEM having a modified surface on which modified surface is exposed a conductive member that is electrically connected to the bond pad.

A4  
Sub B1  
19. (Amended) The method of Claim 2 wherein the removing step is accomplished through grinding.

A4  
Sub B1  
20. (Amended) The method of Claim 47 wherein the PEM comprises a thin small outline package (TSOP) containing a gold ball bond, a lead frame, and a wire that are collectively encapsulated in the plastic body of the PEM, wherein the gold ball bond is formed on the bond pad, wherein the wire connects the gold ball bond to the lead frame, and wherein the gold ball bond is the conductive member exposed on the modified surface of the modified PEM through thinning.

Please add the following claims 46 and 47:

A5  
Sub B1  
46. The method of Claim 1 wherein the PEM's encapsulant is a plastic body.

47. The method of Claim 46 wherein the conductive member that is electrically connected to the bond pad is encapsulated in the plastic body of the PEM and wherein the removing step comprises thinning a first side of the PEM to expose the conductive member.